

BGB719N7ESD

Low Noise Amplifier MMIC for FM Radio Applications

Data Sheet

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BGB719N7ESD, Low Noise Amplifier MMIC for FM Radio Applications

Revision History: 2012-10-30, Revision 1.1

Page	Subjects (changes since previous revision)
	This data sheet replaces the revision from 2011-10-10. The product itself has not been changed and the device characteristics remain unchanged. Only the product description and information available in the data sheet have been expanded and updated.

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Table of Contents

	Table of Contents	4
	List of Figures	5
	List of Tables	6
1	Product Brief	7
2	Features	8
3	Pin Configuration	9
4	Functional Block Diagram	10
5	Maximum Ratings	11
6	Thermal Characteristics	12
7	Operation Conditions	12
8	Electrical Characteristics	13
8.1	DC Characteristics	13
8.1.1	Typical DC Characteristic Curves	13
8.2	AC Characteristics	14
8.2.1	Typical AC Characteristic Curves	14
9	Package Information TSNP-7-6	16

List of Figures

Figure 3-1	Pinning of BGB719N7ESD in TSNP-7-6	9
Figure 4-1	Functional Block Diagram	10
Figure 4-2	Application Board Drawing	10
Figure 6-1	Total Power Dissipation $P_{\text{tot}} = f(T_s)$	12
Figure 8-1	I_{CC} as a function of V_{CC} , $V_{\text{Ctrl}} = 3 \text{ V}$	13
Figure 8-2	Input and Output matching curves	14
Figure 8-3	I_{CC} as a function of T_A	15
Figure 9-1	Package Outline	16
Figure 9-2	Package Footprint	16
Figure 9-3	Marking Description (Marking BGB719N7ESD: AC)	16
Figure 9-4	Tape Dimensions	16

List of Tables

Table 3-1	Pinning Table	9
Table 4-1	Bill of Materials	10
Table 5-1	Maximum Ratings at $T_A = 25\text{ °C}$	11
Table 5-2	ESD Robustness	11
Table 6-1	Thermal Resistance	12
Table 7-1	Operation Conditions at $T_A = 25\text{ °C}$	12
Table 8-1	DC Characteristics at $T_A = 25\text{ °C}$	13
Table 8-2	AC characteristics in the FM Radio LNA Application	14

1 Product Brief

So-called active antenna modules containing a unique passive structure tailored for FM radio and directly interfaced to appropriate amplifier circuitry are rapidly gaining market acceptance in emerging mobile device applications. High gain, low noise amplifiers with small footprints and high robustness against electrostatic discharge are key components for these active antenna designs. The BGB719N7ESD fulfills all the necessary criteria for such active antennas and is able to solve the main problems in embedded active FM antenna designs for handset devices enhancing the receiver sensitivity and consuming less power and less board space.

The device is based on Infineon Technologies' cost effective Silicon Germanium (SiGe:C) technology and comes in a small leadless green package with visible leads enabling optical inspection of soldering quality.

2 Features

- High performance FM Radio LNA with integrated biasing
- Frequency range: 10 MHz to 1 GHz
- Low external parts count
- Super miniature low profile leadless package TSNP-7-6, 1.26 x 1.4 x 0.37 mm
- High gain at only 2.8 mA current consumption
- Integrated active biasing circuit enables stable operating point against temperature-, supply voltage- and processing-variations
- Integrated ESD protection for all pins (1.5 kV, HBM)
- High input compression point
- High input impedance
- Excellent noise figure from latest SiGe:C technology
- Supply voltage: 1.5 V to 4.0 V
- Power-off function
- Pb-free (RoHS compliant) and halogen-free package
- Qualification report according to AEC-Q101 available



Applications

- Low noise amplifier and active matching for FM reception with small antennas in all kinds of mobile devices such as cell phones, PDAs, portable FM Radio, MP3 players
- Low noise amplifier at 13.56 MHz for Near Field Communication (NFC) applications

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions

Product Name	Package	Marking
BGB719N7ESD	TSNP-7-6	AC

3 Pin Configuration

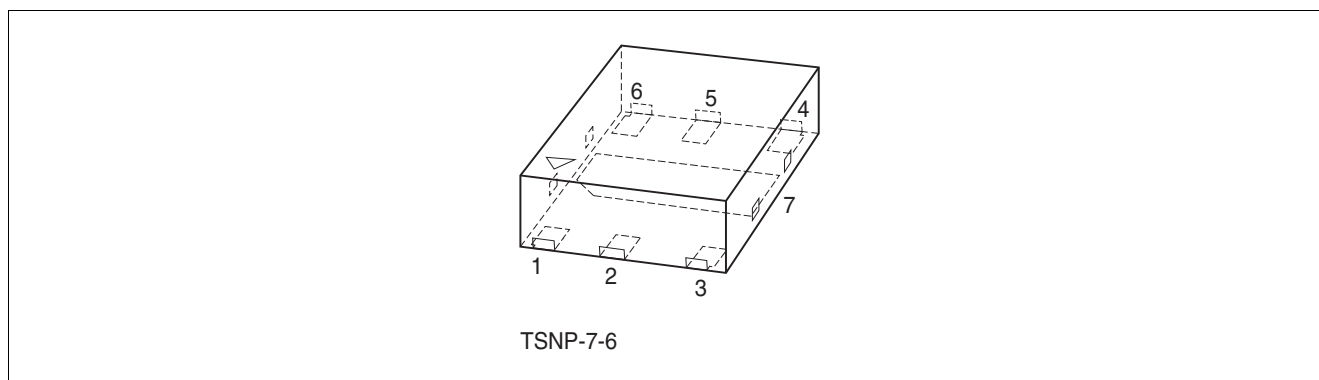


Figure 3-1 Pinning of BGB719N7ESD in TSNP-7-6

Table 3-1 Pinning Table

Pin	Name	Function
1	V_{Ctrl}	On/Off control voltage
2	RF_{IN}	RF input
3	GND_{RF}	RF GND
4	NC	Not connected
5	RF_{OUT}	RF output
6	V_{CC}	Supply voltage
7	GND_{DC}	DC GND

5 Maximum Ratings

Table 5-1 Maximum Ratings at $T_A = 25\text{ }^{\circ}\text{C}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage	V_{CC}	–	–	4.0	V	–
Supply current at V_{CC} pin	I_{CC}	–	–	25	mA	–
DC current at RF_{IN} Pin	I_B	–	–	3	mA	–
On/Off control voltage	V_{ctrl}	–	–	V_{CC}	V	–
Total power dissipation ¹⁾	P_{tot}	–	–	100	mW	$T_S \leq 112\text{ }^{\circ}\text{C}$
Junction temperature	T_J	–	–	150	$^{\circ}\text{C}$	–
Storage temperature	T_{Stg}	-55	–	150	$^{\circ}\text{C}$	–

1) T_S is the soldering point temperature. T_S is measured at the GND pin (7) at the soldering point to the pcb

Table 5-2 ESD Robustness

Testing Model	Standard	Value	Unit
Human Body Model	JESD22-A114-B	1500	V

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.

6 Thermal Characteristics

Table 6-1 Thermal Resistance

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Junction - soldering point ¹⁾	R_{thJS}	–	375	–	K/W	

1)For the definition of R_{thJS} please refer to Application Note AN077 (Thermal Resistance Calculation)

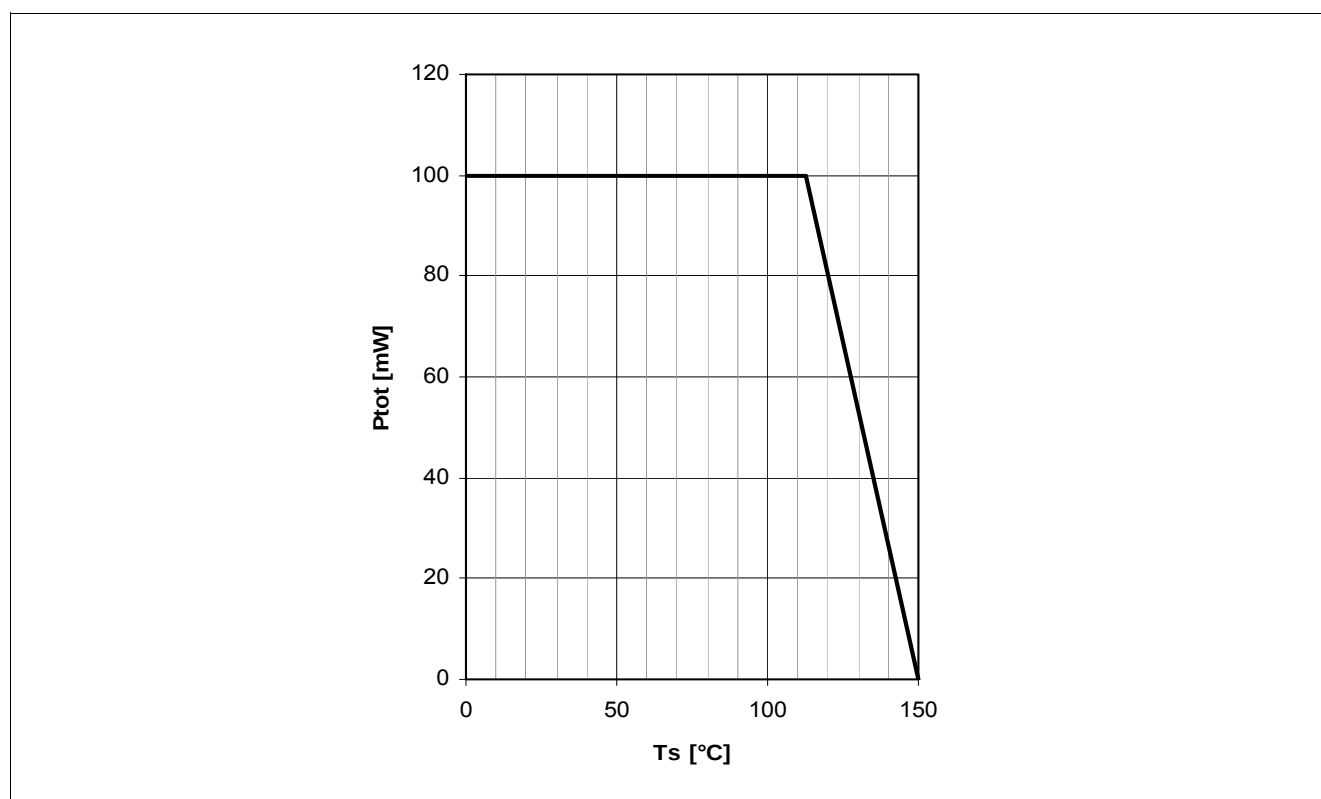


Figure 6-1 Total Power Dissipation $P_{tot} = f(T_s)$

7 Operation Conditions

Table 7-1 Operation Conditions at $T_A = 25\text{ °C}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage	V_{CC}	1.5	3.0	4.0	V	–
Voltage Ctrl On/Off pin in On mode	$V_{ctrl-on}$	1.2	3.0	V_{CC}	V	–
Voltage Ctrl On/Off pin in Off mode	$V_{ctrl-off}$	-0.3	0	0.3	V	–

8 Electrical Characteristics

8.1 DC Characteristics

Table 8-1 DC Characteristics at $T_A = 25\text{ °C}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply current	I_{CC}	2.3	2.8	3.3	mA	$V_{CC} = 3\text{ V}$ $V_{ctrl} = 3\text{ V}$ Small signal operation
Supply current in Off mode	I_{CC-off}	–	1	6	μA	$V_{CC} = 4.0\text{ V}$ $V_{ctrl} = 0\text{ V}$
Current into Ctrl On/Off pin in On mode	$I_{ctrl-on}$	–	6	9	μA	$V_{CC} = 3\text{ V}$ $V_{ctrl} = 3\text{ V}$
Current into Ctrl On/Off pin in Off mode	$I_{ctrl-off}$	–	–	0.3	μA	$V_{CC} = 4.0\text{ V}$ $V_{ctrl} = 0\text{ V}$

8.1.1 Typical DC Characteristic Curves

The measurement Setup is an application circuit according to [Figure 4-1](#). $T_A = 25\text{ °C}$

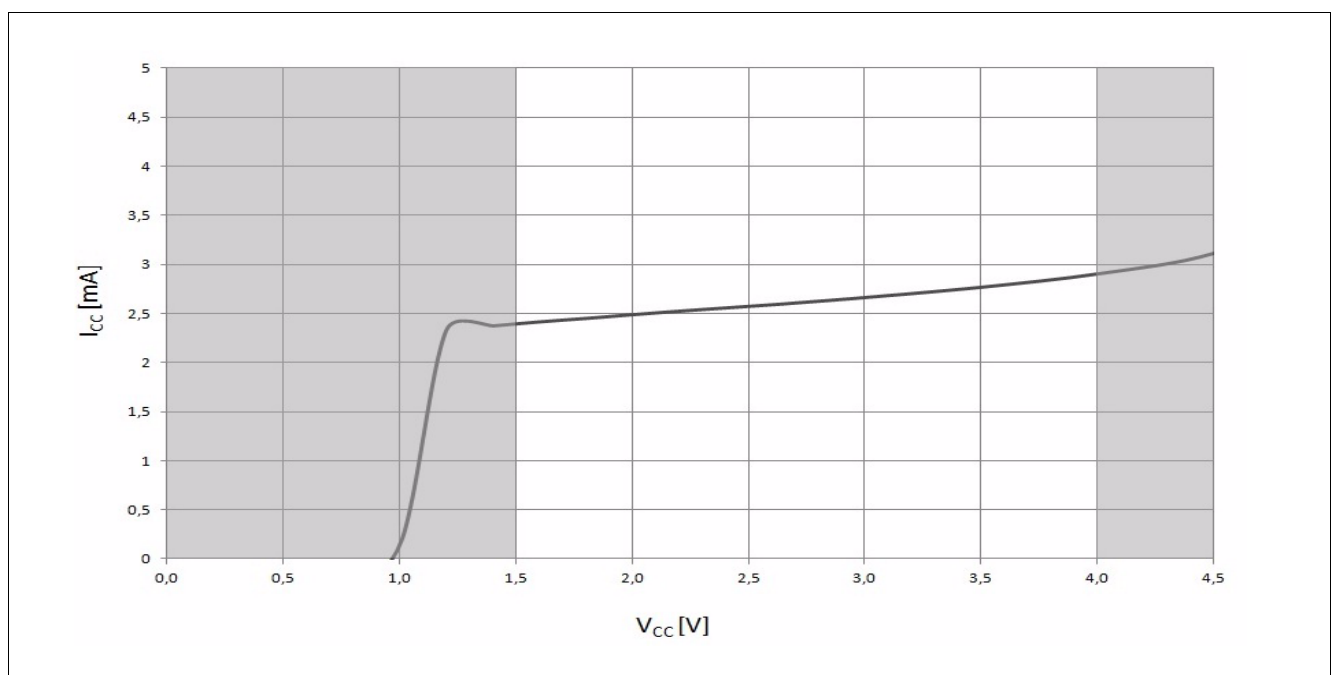


Figure 8-1 I_{CC} as a function of V_{CC} , $V_{ctrl} = 3\text{ V}$

8.2 AC Characteristics

Table 8-2 AC characteristics in the FM Radio LNA Application¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Insertion power gain	$ S_{21} ^2$		13.5		dB	–
Input return loss ²⁾	RL_{IN}	–	0.5 ³⁾	–	dB	–
Output return loss ²⁾	RL_{OUT}	–	11	–	dB	–
Noise figure ⁴⁾	NF_{50}	–	1.2	–	dB	$Z_S = 50 \Omega$
Input 1dB gain compression point ²⁾	IP_{-1dB}	–	-6	–	dBm	–
Input 3rd Order Intercept Point ²⁾	IIP_3	–	-14	–	dBm	$P_{RFIN} = -30 \text{ dBm}$

1) As described in AN255, $T_A = 25^\circ\text{C}$, $V_{CC} = 3 \text{ V}$, $V_{Ctrl} = 3 \text{ V}$, $f = 100 \text{ MHz}$

2) Verified by random sampling

3) High LNA input impedance leads to power matching with high ohmic antennas

4) A low pass filter prevents radio broadcast signals from distorting the NF measurement

8.2.1 Typical AC Characteristic Curves

The measurement Setup is an application circuit according to [Figure 4-1](#). $T_A = 25^\circ\text{C}$

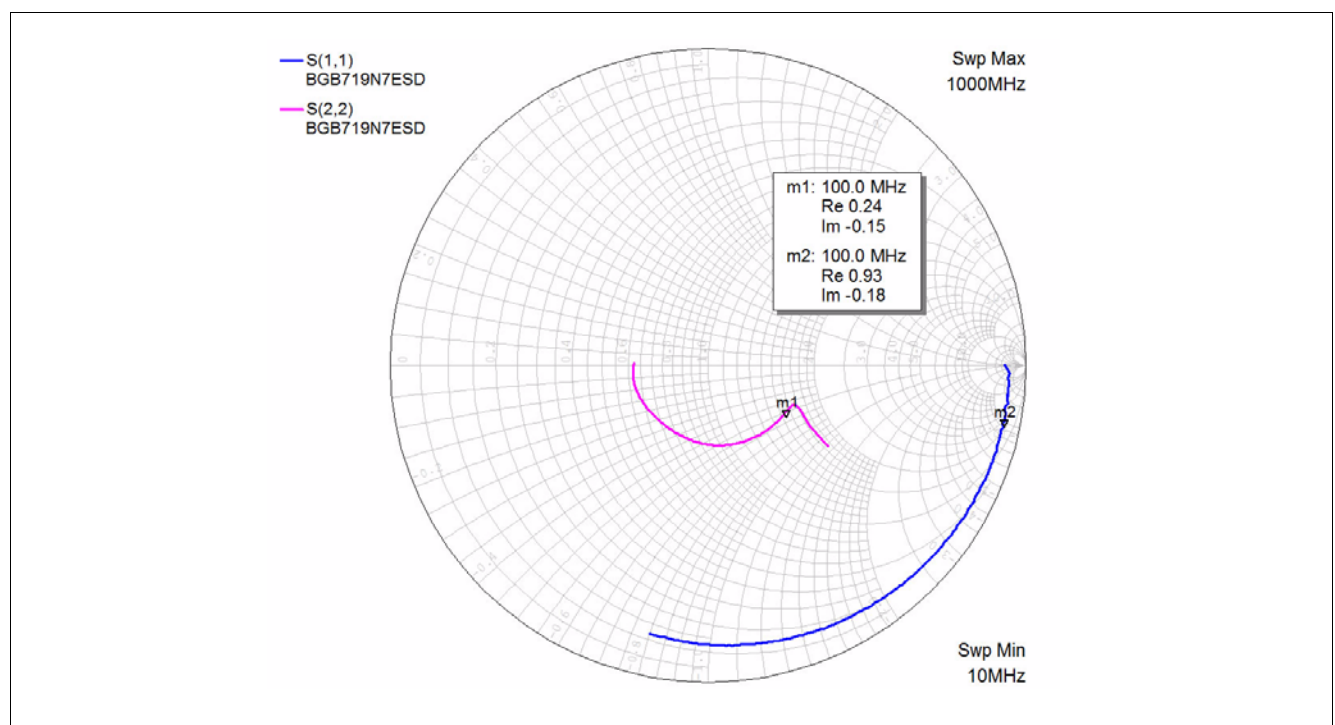


Figure 8-2 Input and Output matching curves

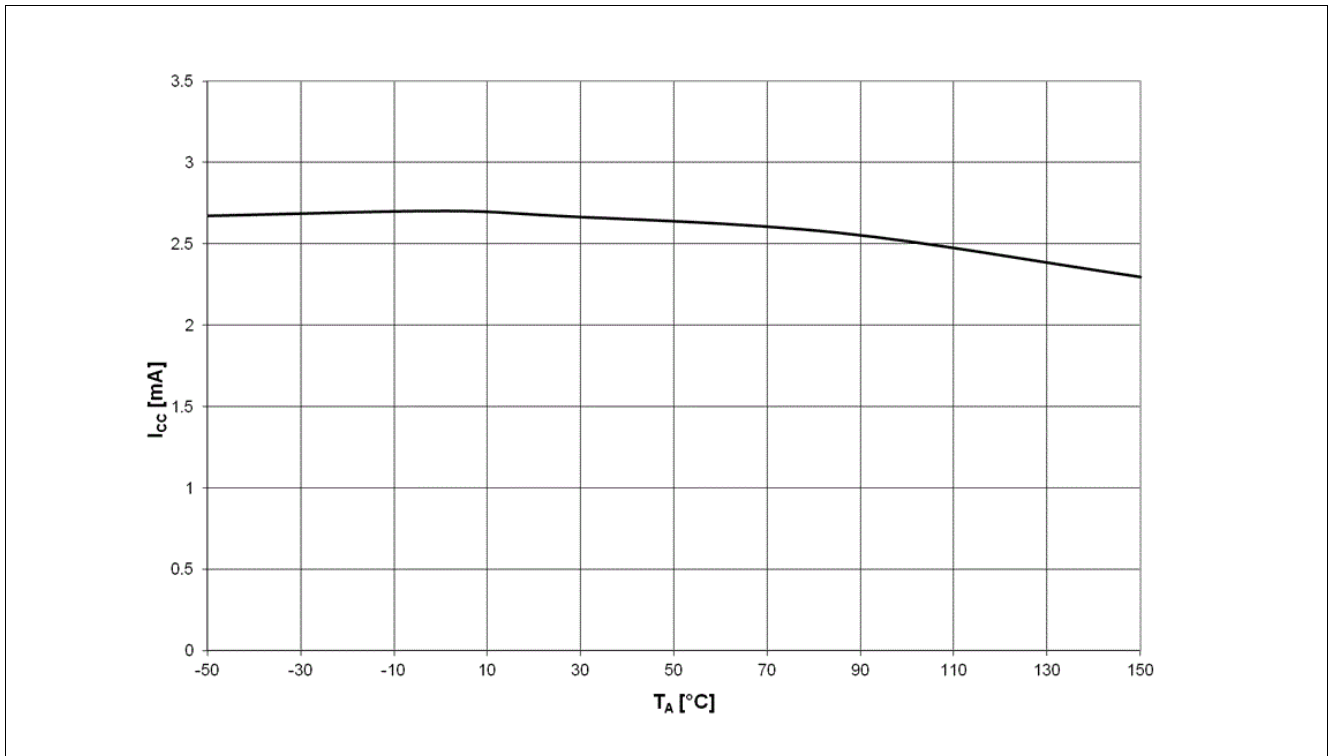


Figure 8-3 I_{CC} as a function of T_A

9 Package Information TSNP-7-6

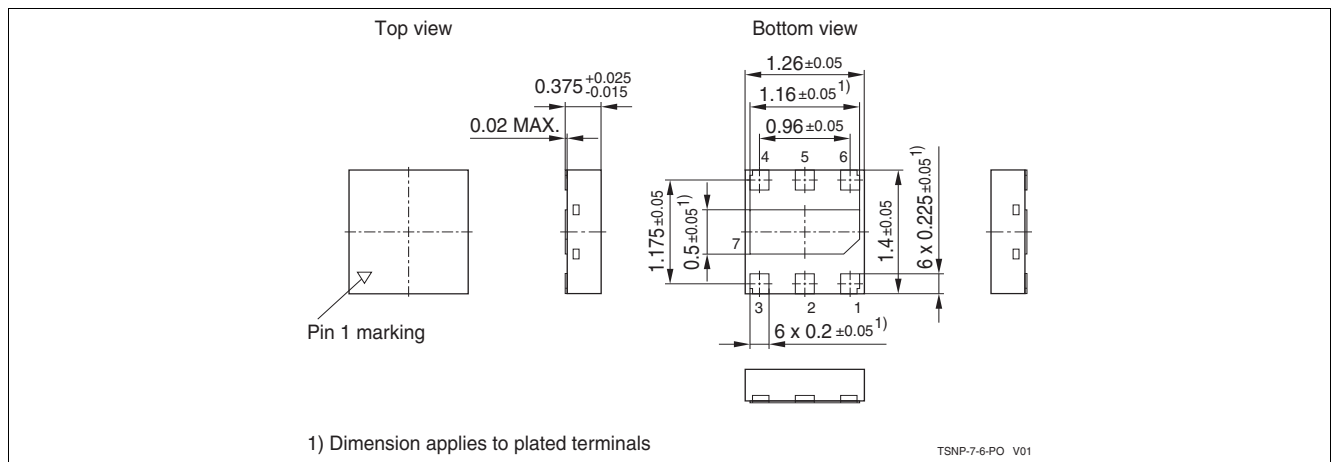


Figure 9-1 Package Outline

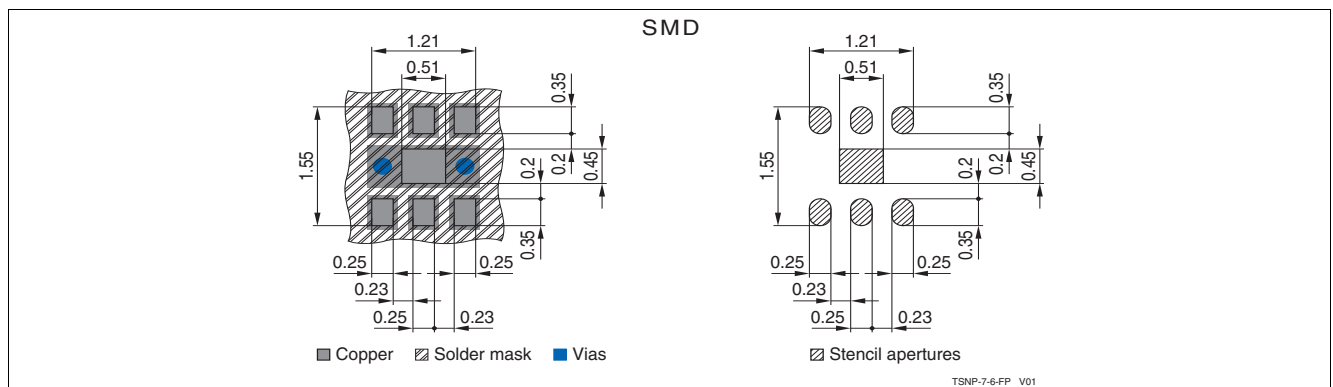


Figure 9-2 Package Footprint

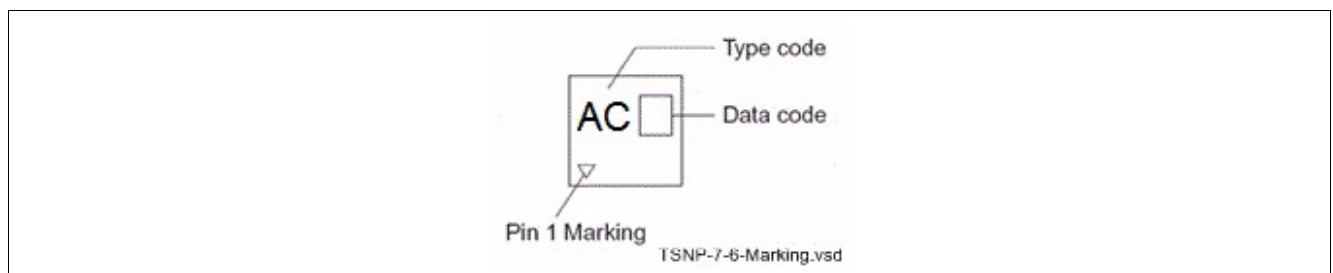


Figure 9-3 Marking Description (Marking BGB719N7ESD: AC)

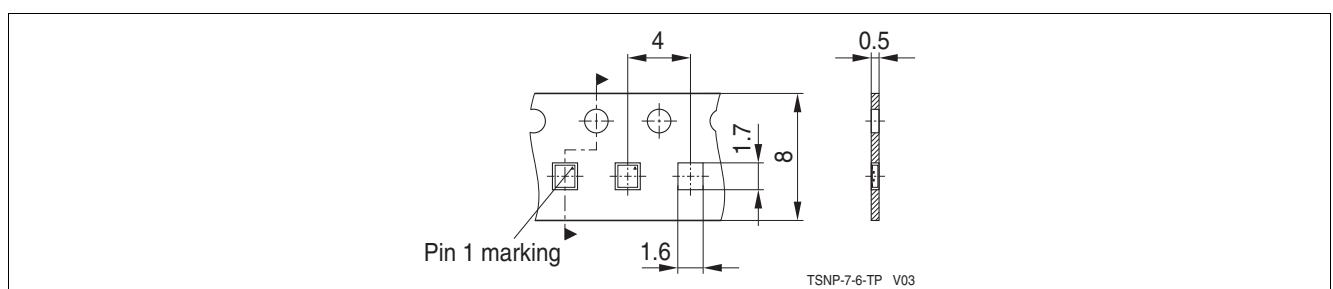


Figure 9-4 Tape Dimensions

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